

HLT2000 Thermal Conductive Gel

BENEFITS AND FEATURES

- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- No pump out and cracking

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & power modules

OVERVIEW

Honeywell HLT2000 is two-part, dispensable thermally conductive gel, which offer long-term reliability and superior softness. The enhanced bonding force between the polymer base and the filler largely improves the thermally conductive gel oil separation issue in storage. Prior to curing, the material maintains good thixotropic characteristics and low viscosity to be easily dispensed. The product can be cured in short time after two-component mixing at room temperature. The high compressibility minimizes thermal resistance at interfaces, while maintaining excellent performance during reliability testing.

STORAGE & USE

- Shelf life 6 months at 0-35°C,
≤65%RH

Property	HLT2000	Test Method
Color	Part A: Yellow Part B: White	Visual
Mix Ratio	1:1	by Volume
Thermal Conductivity (W/m·K)	2.0	ASTM D5470
Thermal Impedance (°C·in ² /W) (1mm@10psi, Typical Value)	0.66	ASTM D5470
Viscosity (Pa·s@25°C)	200-350	ASTM D2196 Brookfield Viscometer, #7 spindle@10rpm
Density(g/cm ³)	2.8	ASTM D792
Hardness (Shore00)	55	ASTM D2240
Minimum BLT (µm)	60	HON Internal
Working Time@25°C (h)	2.0	HON Internal
Curing Time	@25°C (h)	18.0
	@120°C (h)	0.5
Dielectric Strength (KV/mm)	10	HON Internal
Volume Resistivity (ohm-cm)	1.0×10 ¹³	ASTM D149
Flammability Rating	V-0(Equivalent)	ASTM D257
Operating Temperature (°C)	-40~200	UL 94
		HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
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 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
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